

WHAT IS CLAIMED IS:

1 1. A multi-substrate package comprising:
2 a housing;
3 a stack of substrates disposed within the housing; and
4 an array of connectors including a plurality of channels supported by
5 the housing, wherein the connectors are movable between extended and retracted
6 positions within the housing and wherein the connectors connect multiple substrates
7 in the extended positions of the connectors to communicate the multiple substrates
8 along the channels.

1 2. The package as claimed in claim 1, further comprising at least
2 one actuator for moving the connectors between the extended and retracted
3 positions.

1 3. The package as claimed in claim 2, wherein the connectors are
2 flexible connectors and wherein the at least one actuator flexes the connectors so that
3 the connectors move between the extended and retracted positions.

1 4. The package as claimed in claim 1, wherein the channels
2 include fluid channels and the connectors include fluid connectors.

1 5. The package as claimed in claim 1, wherein the channels
2 include electrical channels and the connectors include electrical connectors.

1 6. The package as claimed in claim 1, further comprising at least
2 one resilient sheet for separating the multiple substrates and applying a force
3 between the connectors and the substrates required for proper communication of the
4 multiple substrates.

1 7. The package as claimed in claim 6, wherein the housing
2 includes a cover for applying a force to the stack and wherein the at least one
3 resilient sheet is compressed by the force to the stack so that the at least one resilient